

Completed Intelligent Appliance with 8th Intel® Whiskey Lake-U SoC Processor



31810DW Series



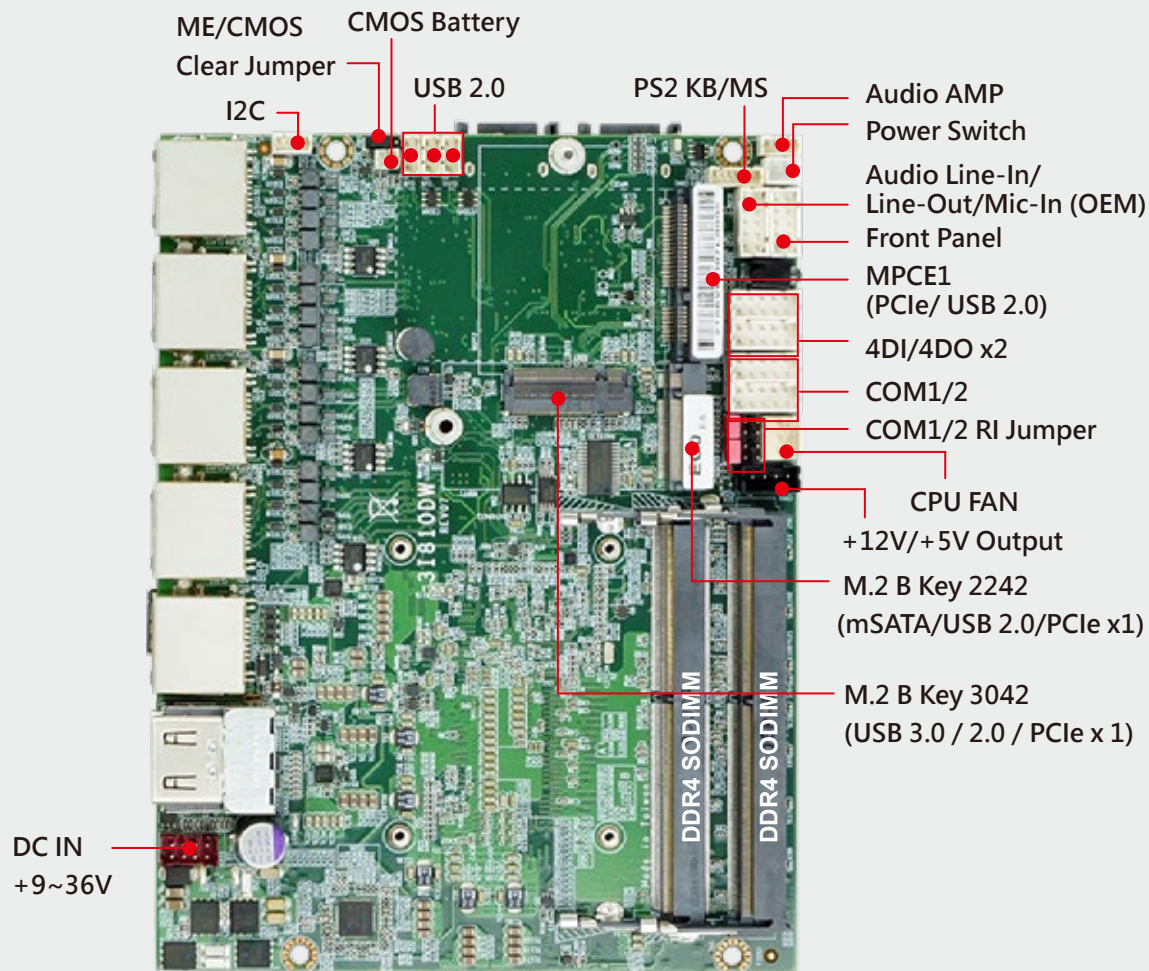
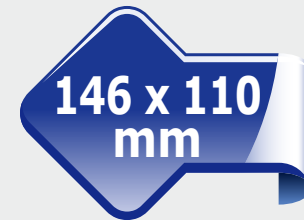


3I810DW

Completed Intelligent Appliance with 8th Intel® Whiskey Lake-U SoC Processor

LEX SYSTEM latest 3.5" SBC 3I810DW is with 8th Gen. Intel® Whiskey Lake-U i7/i5/i3/Celeron processor, integrated 5 x GbE LAN, 7 x USB, 2 x COM and 2 x HDMI & eDP display interface & plus with wide range +9~36V DC input that offers the ideal platform for high performance applications in AI, Smart Automation, Machine Vision, In-vehicle, Industry 4.0 and any compact high-performance Internet of Things (IoT) applications.

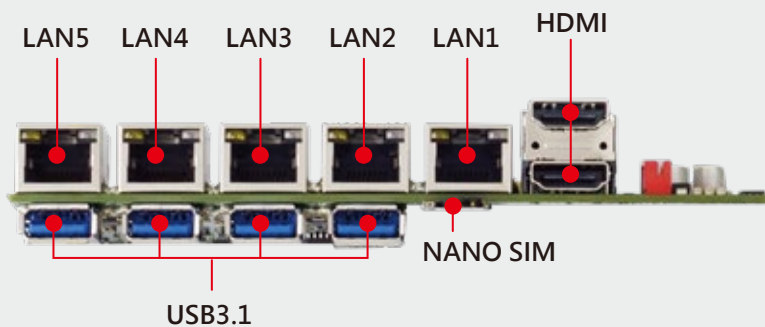
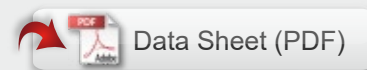
Function MAP



31810DW

Next Gen. solution for Intelligent Appliance

- 8th Intel® Whiskey Lake-U i7 /i5 /i3 /Celeron SoC CPU / chipset
- 2 x DDR4 SODIMM socket, max. up to 64GB
- Display Interface: 2 x HDMI
- 5 x Intel (1x I219LM+4xI210 IT) GbE, 4x USB 3.1,
- 3 x USB 2.0, 2 x COM (RS232/422/485), 8DI/8DO
- 1 x Mini PCIe, 2 x M.2 B Key support NVME
- TPM 2.0 (Optional)
- Wide Range DC-IN 9~36V
- Wide temperature support of -20°C ~ 70°C





TASK 3I810DW

TASK

Dimension: 77 H x 210W x 125D mm

- Super Excellent heat-dissipating System
- Robust & Powerful Fanless Embedded solution

